

# **AN ELECTRONIC DEVICE AND A METHOD OF MANUFACTURING THE SAME**

## **ABSTRACT OF THE DISCLOSURE**

An electronic device comprising: a semiconductor chip having plural electrode pads on one main surface thereof; a wiring board having plural connection parts on one main surface thereof; and plural salient electrodes disposed respectively between the electrode pads of the semiconductor chip and the connection parts of the wiring board to provide electrical connections between the two, the salient electrodes being arranged in an array not taking balance of the semiconductor chip with respect to one main surface of the wiring board, the plural connection parts of the wiring board being arranged at a deeper position than one main surface of the wiring board in a depth direction from the one main surface.

Figure 3